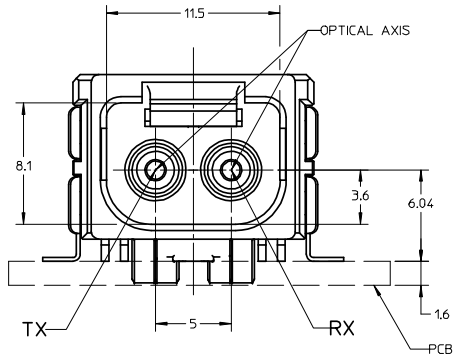
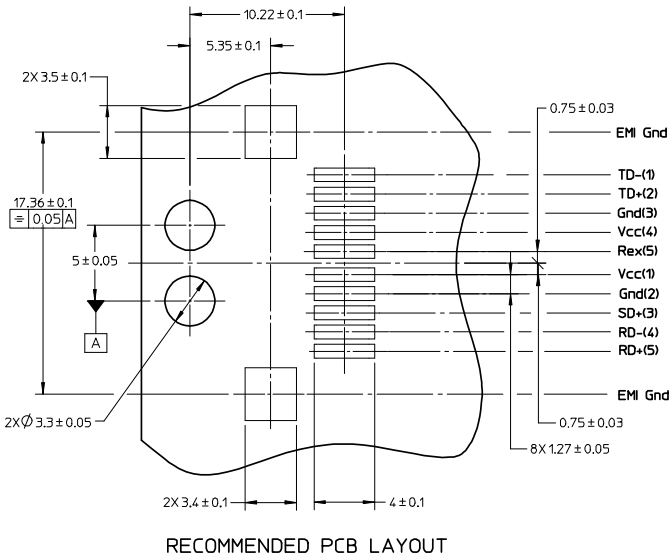
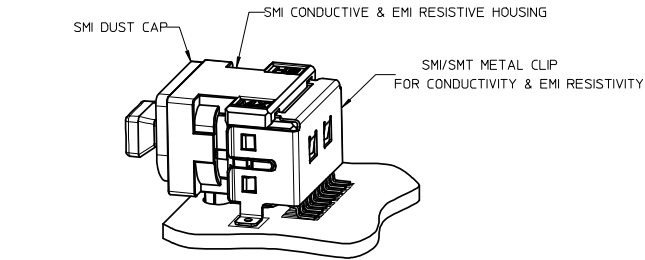
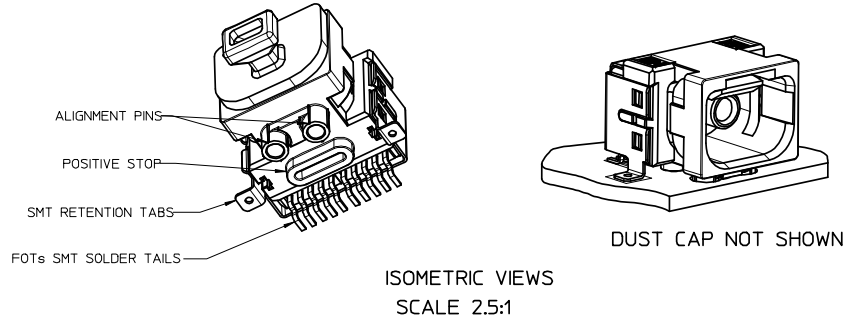
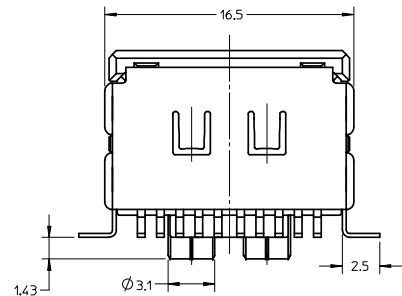
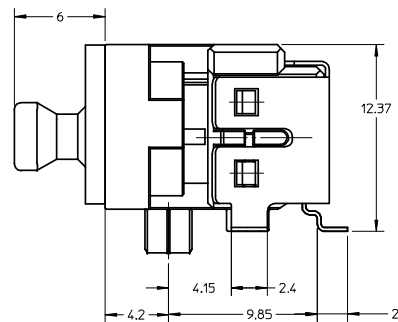
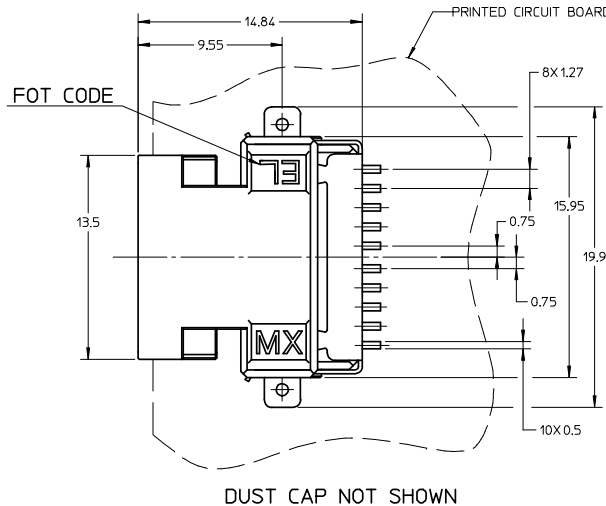


SMI/SMT TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061082200	IEEE-1394/ DIGITAL FDL300K	IE
1061083200	10/100 ETHERNET EDL300K	EL
1061084200	INDUSTRIAL DATA LINK IDL300K	ID



SMI TRANSCEIVER ASSEMBLY
MOUNTED ON THE PCB
DUST CAP NOT SHOWN



- NOTE:
1. ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.
2. ATTACHMENT OF THE COMPONENT TO THE PCB SHALL BE VIA HOT BAR, LASER OR IR SOLDERING.
RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME.

ENTER DESCRIPTION EC NO: MF2008-0555 DRWN:SM IGO 2008/06/11 CHKD: 2008/06/11 APPR:SM IGO 2008/06/26 REV: B	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		4:1	METRIC			
				DRAWN BY DATE		TITLE				
				BG 09/12/06		SMI TRANSCEIVER ASSEMBLY				
				CHECKED BY DATE		SURFACE MOUNT SOLDERING				
				SE 9/15/06						
				APPROVED BY DATE		MOLEX MOLEX INCORPORATED				
				MATERIAL NO.		DOCUMENT NO.				SHEET NO.
				SEE TABLE		SD-106108-X200				1 OF 1
				SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				